STPS0530Z

life.augmented

Schottky rectifier

Datasheet - production data



Description

Single Schottky rectifier suited for switch mode power supplies and high frequency DC to DC converters.

Packaged in SOD-123, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications. Due to the small size of the package this device fits GSM and PCMCIA requirements.

Table 1. Device summary

I _{F(AV)}	0.5 A
V _{RRM}	30 V
V _F (max)	0.33 V

Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching

This is information on a product in full production.

Characteristics 1

Symbol	Parameter	Value	Unit	
V _{RRM}	Repetitive peak reverse voltage		30	V
I _{F(RMS)}	Forward rms current		2	А
I _{F(AV)}	Average forward current $\delta = 0.5$ $T_a = 55 \text{ °C}$		0.5	А
I _{FSM}	Surge non repetitive forward current	5.5	А	
dV/dt	Critical rate of rise of reverse voltage	10000	V/µs	
T _{stg}	Storage temperature range	-65 to +150	°C	
Тj	Operating junction temperature range ⁽¹⁾	-40 to +150	°C	
ΤL	Maximum temperature for soldering dur	260	°C	
$\frac{dPtot}{dPtot} < \frac{1}{dPtot}$ condition to avoid thermal runaway for a diode on its own beatsink				

Table 2. Absolute ratings (limiting values)

1. $\frac{\alpha P \tau o \tau}{dTj} < \frac{1}{Rth(j-a)}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R _{th(j-a)}	Junction to ambient	340 ⁽¹⁾	°C/W
	2		

1. Copper area on PCB S = 2.5 mm^2

Symbol	Parameter	Test conditions		Тур.	Max.	Unit
		T _j = 25 °C			12	μA
I _R ⁽¹⁾ Reverse leakage cu	Povorao lookogo ourront	T _j = 125 °C	V _R = 15 V	3	5	mA
	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}		130	μA
		T _j = 125 °C		9	21	mA
	V _F ⁽²⁾ Forward voltage drop	T _j = 25 °C	I _F = 0.1 A		0.375	
V _F ⁽²⁾		T _j = 125 °C		0.20	0.22	V
		T _j = 25 °C			0.43	
		T 405.00	Ι _F = 0.5 Α	0.04	0.00	

T_i = 125 °C

Table 4. Static electrical characteristics

1. Pulse test: tp = 5 ms, δ < 2%

2. Pulse test: tp = 380 μ s, δ < 2%

To evaluate the maximum conduction losses use the following equation: P = 0.23 x $I_{F(AV)}$ + 0.18 ${I_F}^2_{(RMS)}$

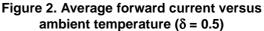


0.31

0.33

current PF(AV)(W) 0.22 $-\delta = 0.1 - \delta = 0.2$ $\delta = 0.05$ δ 0.5 0.20 0.18 0.16 0.14 0.12 0.10 0.08 0.06 0.04 0.02 IF(AV)(A) ⊷tp δ=tp/T 0.00 0.0 0.1 0.2 0.3 0.4 0.5 0.6

Figure 1. Conduction losses versus average Fig



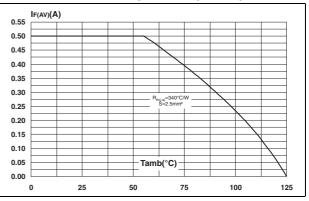


Figure 3. Non repetitive surge peak forward current versus overload duration (maximum values)

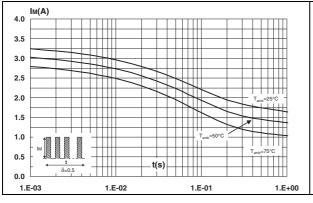


Figure 5. Reverse leakage current versus reverse voltage applied (typical values)

Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration

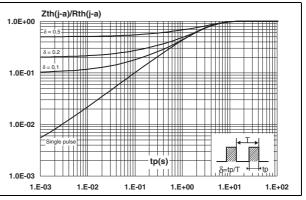


Figure 6. Reverse leakage current versus junction temperature (typical values)

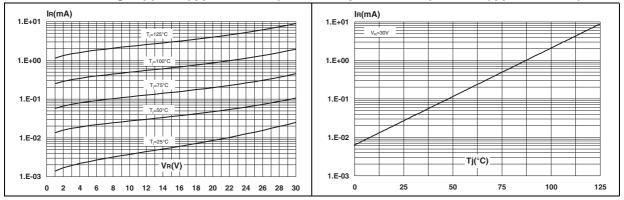
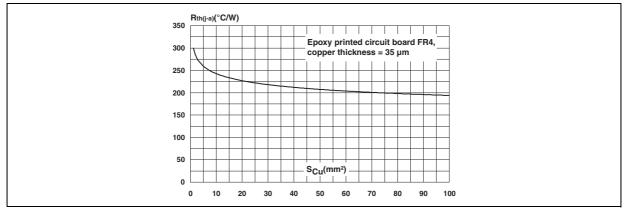




Figure 7. Junction capacitance versus reverse voltage applied (typical values) current C(pF) IFM(A) 1000 2.0 F=1MHz + 1.8 T_j=125°C 1.6 1.4 1.2 T_i=125°C 100 1.0 0.8 0.6 0.4 VR(V) 0.2 VFM(V) 10 0.0 1 10 100 0.00 0.10 0.20 0.30 0.40 0.50 0.60 0.70 0.80

Figure 8. Forward voltage drop versus forward

Figure 9. Thermal resistance junction to ambient versus copper surface under each lead (typical values)





2 Package information

- Epoxy meets UL94, V0.
- Band indicates cathode.

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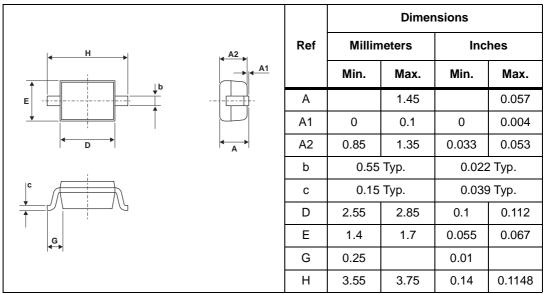
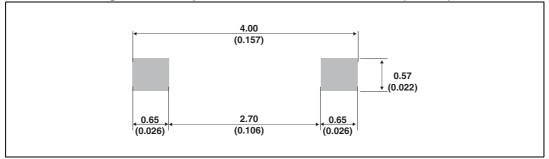


Table	5.	SOD-123	dimensions
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Figure 10. F	Footprint -	dimensions	in millimeters	(inches)
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3 Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS0530Z	Z53	SOD-123	0.01 g	3000	Tape and reel

4 Revision history

Table 7. Document revi	ision	historv
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Date	Revision	Changes
Mar-2003	1A	Initial release.
17-Oct-2006	2	Reformated to current standards. Updated maximum junction temperatures to 150 °C and updated package illustration to show cathode bar on page 1
23-Apr-2014	3	Updated Tj max to Tj range in <i>Table 2</i> .



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